ICEPT2020

21st International Conference on Electronic Packaging Technology

August 12~15, 2020

Guangzhou, China

2nd Call for Papers

2020 21st International Conference on Electronic Packaging Technology (ICEPT) will be held in Guangzhou, China, from *August 12 to 15, 2020*. ICEPT 2020 is hosted by Institute of Microelectronics of Chinese Academy of Sciences (IMECAS), technically sponsored by IEEE Electronics Packaging Society (IEEE-EPS), Electronic Manufacturing and Packaging Technology Society of Chinese Institute of Electronics (CIE-EMPT), organized by Guangdong University of Technology, and co-organized by National Center for Advanced Packaging Co., Ltd. (NCAP China). As one of the most famous international conferences on electronic packaging technology, the conference has received strong support from IEEE- EPS and high praise from Chinese Institute of Electronics (CIE) and China Association for Science and Technology (CAST). At present, Moore's Law has reached an inflection point, semiconductor manufacturing technology is facing challenges, and new technologies are constantly emerging. This conference will provide an academic communication platform for new progresses and new ideas in electronic packaging and manufacturing technology for experts, scholars and researchers from academia and industry worldwide.

During the four-day event, participants from nearly 20 countries and region will share the latest technological developments of electronic packaging technologies via special lectures, invited talks, theme forums, technical sessions, exhibitions, poster presentations and other forms. We sincerely invite you to join in this event!

CONFERENCE TOPICS

- ✧ **Advanced Packaging**: 2.5D and 3D packaging, wafer-level and panel-level packaging, flip chip, advanced packaging substrate technologies, system integration, heterogeneous/hybrid integration, packaging design and process.
- ✧ **Packaging Materials & Processes**: New packaging materials, green materials, nano-materials, and related packaging materials for packaging/assembly processes.
- ✧ **Packaging Design & Modeling**: Design, modeling, methodology, and simulation for system integration and packaging; methodology and simulation for electrical/thermal/optical/mechanical models, multi-scale and multi-physics modeling, process simulation.
- ✧ **Interconnection Technologies**: TSV, bumping and micro copper pillar technologies, high density inter-connection technologies, nano-materials bonding technologies, interposer, redistribution layer technologies for fan-in and fan-out packaging, chip-to-wafer/panel and wafer-to-wafer interconnect technologies, thermocompression bonding, non-conventional inter-connection technologies.
- ✧ **Advanced Manufacturing & Packaging Equipment**: Assembly, testing, manufacturing, automation technologies and equipment for Packaging manufacturing.
- ✧ **Quality & Reliability**: Test technologies for packaging, quality monitoring and evaluation, methodologies for reliability data collection and analysis, reliability modeling, life prediction, failure analysis and non-destructive diagnose.
- ✧ **Power Electronics**: Thermal management, interconnection and substrate technologies for power electronics, switch module, isolated/non-isolated power converter, inverter module, IPM, POL, PwrSoC, PSiP, open frame, electrical design, magnetic integration, control algorithm, firmware development, EMI modeling & optimization.
- ✧ **Optoelectronics and New Display**: Optoelectronics and solid state lighting design, simulation, interconnection, packaging & integration, display module encapsulation & assembly, new display device and module encapsulation & assembly, mass Transfer of MicroLED, wearable, bendable, foldable and flexible electronics and display.
- ✧ **MEMS & Fan-out Packaging**: MEMS, NEMS, sensor, sensor packaging, implantable device packaging, microfluidics, nano-battery. 3D printing, self-alignment and assembly, wafer-level and panel-level packaging, redistribution layer, reliability, new structure and technologies for fan-out packaging.
- ✧ **Emerging Technologies**: Electrical modeling, analysis, design, integration, fabrication and characterization of novel devices, packages, and systems for RF/microwave and high-speed I/O, component optimization and power management of computing/communication systems, 5G mobile networking, wearable/flexible electronics and bio-electronics, etc.

IMPORTANT DATES

❑ ~~March 20, 2020~~	~~Deadline for Submission of Abstract~~
❑ **April 4, 2020**	**Deadline for Submission of Abstract**
❑ **April 17, 2020**	**Notification of Abstract Acceptance**
❑ **May 20, 2020**	**Deadline for Submission of Full Paper**
❑ **June 10, 2020**	**Notification of Full Paper Acceptance**
❑ **June 20, 2020**	**Deadline of Final Paper Submission**

SUBMISSION OF ABSTRACT

Abstracts are solicited to describe original and unpublished work. The abstract should be approx. 500 words and contains a clear statement of the background, methodology, results, and conclusions. All abstracts and manuscripts must be in English and should be submitted through online submission system**.** The instructions for abstract submission can be found at the conference website **http://www.icept.org**. All accepted manuscripts will be submitted for inclusion into IEEE Xplore. Selected papers will be recommended for publication in related IEEE/EPS journals.

BEST PAPER AWARD

Best Papers and Posters will be selected and awarded at the conference.

CALL FOR EXHIBITION/SPONSORSHIP

A tabletop exhibition featuring suppliers of materials, equipment, components, software, manufacturers, and service providers of the electronics packaging and related industries will be held during the conference. Potential exhibitors and sponsors may e-mail to **icept2020@gdut.edu.cn** for details.

General Chairs:	**Tianchun YE**	**Xin CHEN**
Technical Chair:	**Chengqiang CUI**	**Liqiang CAO**
Organizing Chair:	**Qiang LIU**	**Wen YIN**

Conference Website: **http://www.icept.org** E-mail: **icept2020@gdut.edu.cn**

ABOUT Guangzhou

As the capital of Guangdong Province, Guangzhou locates at the center of Guangdong-Hong Kong-Macao Greater Bay Area, which is one of the largest urban agglomerations in the world. Since the 3rd century AD, Guangzhou has become the main port of the Maritime Silk Road and a political, military, economic, cultural, scientific and educational center in South China. Today's Guangzhou has attracted a large number of businessmen and high-tech enterprises, brought together 80% of colleges and universities and 70% of scientists and technologists in the province. The city has become an energetic international trade center and comprehensive transportation hub, and is hailed as China's southern gate to the world.

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